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**China Hongguang Holdings Limited**

**中國宏光控股有限公司**

*(Incorporated in the Cayman Islands with limited liability)*

**(Stock Code: 8646)**

**VOLUNTARY ANNOUNCEMENT  
LATEST BUSINESS DEVELOPMENTS  
GUANGDONG LONGGUANG’S COMPLETION OF ENTERPRISE  
STANDARD FILING FOR THE MANUFACTURING PROCESS OF  
TGV GLASS-CORE COPPER-CLAD LAMINATES**

This announcement is voluntarily issued by China Hongguang Holdings Limited (the “**Company**”, together with its subsidiaries, the “**Group**”) to provide the Company’s shareholders and potential investors with an update on the Group’s latest progress in the field of core new materials technology. This announcement does not constitute a mandatory disclosure under Rule 17.10 of the GEM Listing Rules of The Stock Exchange of Hong Kong Limited (the “**GEM Listing Rules**”), nor does it constitute any forecast or guarantee regarding the Group’s future profitability or share price performance.

**BACKGROUND TO THE FILING**

The board (the “**Board**”) of directors (the “**Directors**”) of the Company is pleased to announce that Guangdong Longguang New Materials Technology Co., Ltd.\* (廣東隆光新材料科技有限公司) (“**Guangdong Longguang**”), an indirect wholly-owned subsidiary of the Group, acting as the standard drafting entity, has led the development of the enterprise standard “Manufacturing Process for TGV Glass-Core Copper-Clad Laminates (《一種TGV玻璃基覆銅板製造工藝》)” (Standard No.: Q/LG 001-2026), which has now completed the filing procedure on the Enterprise Standard Information Public Service Platform. The standard was published on 1 July 2022 and is scheduled to come into force on 1 July 2026.

This standard was proposed by Guangdong Longguang, which is responsible for its drafting and interpretation. The principal drafter is Jiyong Li. The text of the standard covers product structure, material composition, manufacturing processes and inspection specifications, and is applicable to high-end application scenarios such as high-frequency millimetre-wave communications, advanced chip packaging and automotive electronics.

## KEY TECHNICAL SPECIFICATIONS AND INDUSTRIAL BREAKTHROUGHS

The products and processes specified in this standard establish differentiated technical barriers in the following areas:

| Technical Indicators                   | Standard Parameters                                                                                     | Competitive Advantages over the Industry                                                    |
|----------------------------------------|---------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------|
| Glass substrate thickness              | 30 $\mu\text{m}$ –100 $\mu\text{m}$<br>(30 $\mu\text{m}$ –50 $\mu\text{m}$ for flexible specifications) | Traditional GCC consists of rigid single sheets; this standard enables roll-form production |
| Dissipation factor (DF)                | $\leq 0.0007$ @ 30GHz                                                                                   | Significantly superior to conventional glass substrates on the market (DF>0.002)            |
| Coefficient of thermal expansion (CTE) | $\leq 2.3$ ppm/ $^{\circ}\text{C}$                                                                      | Meets the thermal management requirements of high-end chip packaging                        |
| Minimum bending radius                 | 12mm (flexible specification)                                                                           | Suitable for roll-to-roll processing, reducing cutting waste by approximately 65%           |
| TGV micro-holes                        | 25 $\mu\text{m}$ –45 $\mu\text{m}$ with a taper of 72°–78°                                              | Pre-formed during the moulding stage, eliminating the need for secondary laser drilling     |
| Coating peel strength                  | $\geq 1.2$ N/mm<br>(no delamination at 260 $^{\circ}\text{C}$ reflow soldering)                         | Meets reliability requirements for high-temperature SMT processes                           |
| Mass production yield rate             | $\geq 93\%$                                                                                             | A significant improvement over conventional processes (<72%)                                |
| Overall cost reduction                 | Approximately 32% lower than conventional processes                                                     | Offers economic viability for large-scale mass production                                   |

## KEY POINTS OF PROCESS INNOVATION

- Utilises a fully electric furnace melting process combined with platinum overflow continuous strip forming technology to achieve roll-to-roll continuous production of glass substrates;
- TGV micro-hole integrated moulding: pre-forming conductive micro-holes simultaneously during the glass overflow moulding process, thereby eliminating the need for laser drilling and mitigating the risks of chipped edges, cracks and voids in the hole walls;
- Gradient composite metal layers: TiCr nano-barrier layer  $\rightarrow$  thin copper transition layer  $\rightarrow$  thickened electrolytic copper layer  $\rightarrow$  OSP anti-oxidation protective layer, forming an anchoring structure to ensure interface reliability in high-temperature and high-humidity environments.

## MARKET PROSPECTS AND STRATEGIC SIGNIFICANCE

The TGV glass-core copper-clad laminate (GCC) covered by this standard is a key material for next-generation high-frequency, high-speed electronic substrates. Its main downstream applications include:

1. In-vehicle millimetre-wave radar: suitable for the 77GHz frequency band, meeting the stringent requirements of autonomous driving systems for low-loss, low-expansion substrates;
2. 6G phased-array antennas: ultra-low dielectric loss supports low-attenuation transmission of millimetre-wave signals;
3. Chiplet/2.5D/3D packaging: low CTE characteristics match the thermal expansion curve of silicon wafers, reducing the risk of packaging warpage;
4. CPO (Co-Packaged Optics): provides high-frequency substrate solutions for optoelectronic co-packaged modules.

The Board believes that the completion of this corporate standard filing marks Guangdong Longguang's establishment of an independent intellectual property system and mass-producible process specifications in the field of TGV glass-core copper-clad laminates, which will help:

- Consolidating technological barriers: establishing process parameters and quality benchmarks in the form of corporate standards provides a foundational basis for subsequent applications for industry standards, national standards and international patent portfolios;
- Accelerating customer certification: a standardised production system helps downstream semiconductor packaging and telecommunications equipment manufacturers shorten supplier onboarding cycles;
- Ensuring compliance with production capacity expansion: providing a basis for technical compliance in relation to Guangdong Longguang's future production line construction, supply chain credit arrangements and capital operations;
- Supporting the Group's valuation: enhancing the value of the Group's assets in the new materials and hard technology sector, in line with the Group's long-term "New Materials+" strategic layout.

## **RISK WARNING AND DISCLAIMER**

**Shareholders and potential investors are advised to note the following:**

- 1. Standard filing does not equate to immediate revenue: the enterprise standard filing is a technical compliance procedure; it does not imply that the relevant products have entered large-scale mass production or that firm sales orders have been secured. Actual commercialisation progress depends on downstream customer certification, production capacity development and market expansion;**
- 2. Risks associated with technological iteration: the new materials industry is characterised by rapid technological iteration; should alternative technical solutions emerge in the future, this may affect the market competitiveness of the products covered by this standard;**
- 3. Uncertainties regarding production capacity ramp-up: there is a time lag between the establishment of a standard and the commencement of production line operations, as well as the stabilisation of yield rates to meet targets; during this period, uncertainties may arise relating to equipment commissioning, process optimisation and the supply of raw materials;**
- 4. Market risk: the pace of industrialisation of downstream applications (such as 6G communications and Chiplet packaging) is influenced by the global macroeconomy, industry policies and technological developments; there is a risk that market uptake may be slower than anticipated;**
- 5. This announcement does not constitute an offer: the information contained in this announcement is for investors' reference only and does not constitute any investment advice, offer or invitation to make an offer. Shareholders and potential investors are advised to exercise due diligence when trading in the Company's shares and to be mindful of investment risks.**

**By Order of the Board**  
**China Hongguang Holdings Limited**  
**LIN Weishan**  
*Chairwoman and Executive Director*

Hong Kong, 4 August 2026

*As at the date of this announcement, the Executive Directors are Mr. WEI Jiakun, Ms. LIN Weishan and Ms. LI Wanna; and the Independent Non-Executive Directors are Ms. MAO Shue, Mr. JIA Xiaogang and Mr. WU Yong.*

*This announcement, for which the Directors collectively and individually accept full responsibility, includes particulars given in compliance with the GEM Listing Rules for the purpose of giving information with regard to the Company. The Directors, having made all reasonable enquiries, confirm that, to the best of their knowledge and belief, the information contained in this announcement is accurate and complete in all material respects and not misleading or deceptive, and there are no other matters the omission of which would make any statement in this announcement misleading.*

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*\* For identification purposes only*